2SC6012

Silicon NPN triple diffusion mesa type

For horizontal deflection output

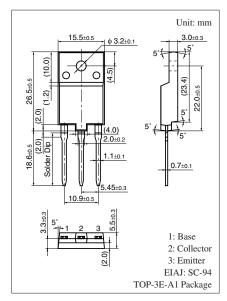
■ Features

- High breakdown voltage, and high reliability through the use of a glass passivation layer
- High-speed switching
- Wide safe oeration area

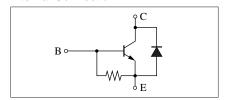
■ Absolute Maximum Ratings $T_C = 25$ °C

Parameter	Symb	ool Rating	Unit	
Collector-base voltage (Emitter open)		D 1700	V	
Collector-emitter voltage (E-B short)		s 1700	V	
Emitter-base voltage (Collector open)		7	V	
Base current	I_{B}	3	A	
Collector current		15	A	
Peak collector current *		24	A	
Collector power dissipation		60	W	
$T_a = 25$	5°C	3		
Junction temperature		150	°C	
Storage temperature		-55 to +150	°C	

Note) *: Non-repetitive peak collector current



Internal Connection

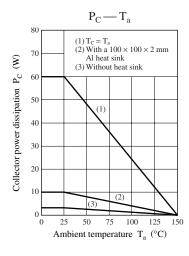


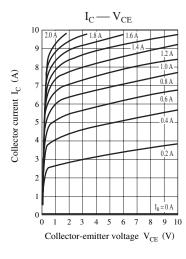
■ Electrical Characteristics $T_C = 25^{\circ}C \pm 3^{\circ}C$

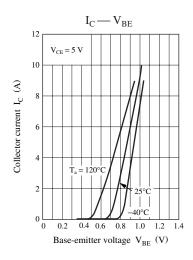
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Emitter-base voltage (Collector open) *	V_{EBO}	$I_E = 750 \text{ mA}, I_C = 0$	7			V
Forward voltage *	V _F	$I_F = 7.0 \text{ A}$			-2	V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 1000 \text{ V}, I_E = 0$			50	μΑ
		$V_{CB} = 1700 \text{ V}, I_E = 0$			1	mA
Forward current transfer ratio *	h_{FE}	$V_{CE} = 5 \text{ V}, I_{C} = 7.0 \text{ A}$	7		12	_
Collector-emitter saturation voltage *	V _{CE(sat)}	$I_C = 7.0 \text{ A}, I_B = 1.75 \text{ A}$			3.0	V
Base-emitter saturation voltage *	V _{BE(sat)}	$I_C = 7.0 \text{ A}, I_B = 1.75 \text{ A}$			1.5	V
Transition frequency	f_T	$V_{CE} = 10 \text{ V}, I_{C} = 0.5 \text{ A}, f = 0.5 \text{ MHz}$		2.1		MHz
Storage time	t _{stg}	I _C = 7.0 A, Resistance loaded			5.0	μs
Fall time	$t_{\rm f}$	$I_{B1} = 1.75 \text{ A}, I_{B2} = -3.5 \text{ A}$			0.5	μs

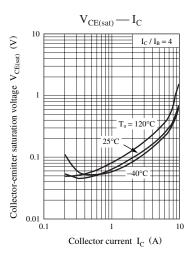
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

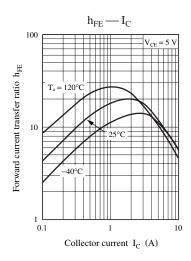
^{2. *:} Pulse measurement

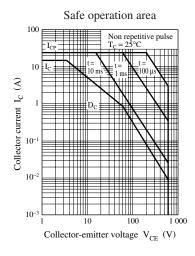




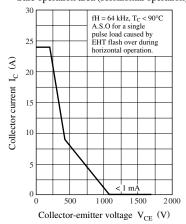








Safe operation area (Horizontal operation)



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